

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A semiconductor single crystal manufacturing apparatus, comprising a chamber disposed in a furnace and having a crucible in which a melt is charged, a heater for heating the crucible, and a wire exposed to the melt disposed within the chamber, wherein:

at least a portion~~region~~ of the wire which is exposed to a high temperature is covered with a collar.

2. (currently amended) The semiconductor single crystal manufacturing apparatus according to claim 1, further including a plurality of collars to cover at least a portion of the wire~~wherein the collar is disposed in plural.~~

3. (currently amended) The semiconductor single crystal manufacturing apparatus according to claim 1 or 2, wherein ~~a~~the collar is disposed between a wire winding device and a seed crystal.

4. (currently amended) The semiconductor single crystal manufacturing apparatus according to Claim 1~~any one of claims 1 through 3~~, wherein the collar is disposed closely to cover the wire.

5. (currently amended) The semiconductor single crystal manufacturing apparatus according to claim 1, wherein the wire having a portion~~region~~ covered with the collar hangs a seed holder which is vertically moved within the chamber, via a coupling member, and a length of at least either of the seed holder or the coupling member is determined to be a length to locate a proximity of a tip end of the exposed region of the wire in a region having a temperature less than a prescribed temperature in a high-temperature atmosphere within the furnace when the seed crystal is attached to the seed holder and located to come into contact with the melt.

6. (previously presented) The semiconductor single crystal manufacturing apparatus according to claim 5, wherein less than the prescribed temperature is less than 700°C.

7. (new) The semiconductor single crystal manufacturing apparatus according to Claim 2, wherein the plurality of collars are disposed closely to cover the wire.

8. (new) The semiconductor single crystal manufacturing apparatus according to Claim 3. wherein the collar is disposed closely to cover the wire.